3SK144

Silicon N-Channel 4-pin MOS FET

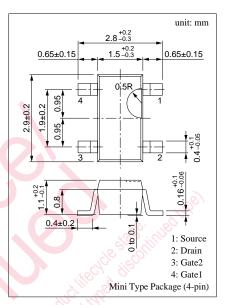
For VHF high-gain and low-noise amplification

■ Features

- Low noise-figure (NF)
- Large power gain PG
- Mini-type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing.

■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit	
Drain to Source voltage	V _{DS}	15	V	
Gate 1 to Source voltage	V _{G1S}	±8	V	
Gate 2 to Source voltage	V _{G2S}	±8	V	
Drain current	I _D	±30	mA	
Allowable power dissipation	P _D	150	mW	
Channel temperature	T _{ch}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: 3E

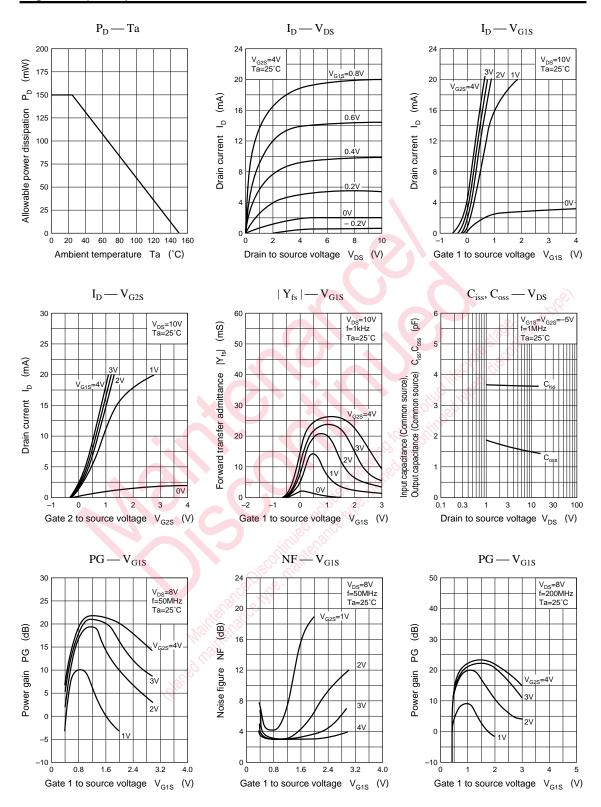
■ Electrical Characteristics (Ta = 25°C)

		2	1.97			
Parameter	Symbol	Conditions	min	typ	max	Unit
Drain current	I_{DSS}^{*2}	$V_{DS} = 10V, V_{G1S} = 0, V_{G2S} = 4V$	0.8		15	mA
Gate 1 cut-off current	I_{G1SS}	$V_{DS} = V_{G2S} = 0, V_{G1S} = \pm 8V$			±20	nA
Gate 2 cut-off current	I_{G2SS}	$V_{DS} = V_{G1S} = 0, V_{G2S} = \pm 8V$			±20	nA
Drain to Source voltage	V_{DSX}	$I_D = 50\mu A$, $V_{G1S} = -5V$, $V_{G2S} = 0$, $R_D = 56\Omega$, $R_S = 270\Omega$	15			V
Gate 1 to Source cut-off voltage	V_{G1SC}	$V_{DS} = 10V, V_{G2S} = 4V, I_D = 100\mu A$		- 0.6	-3	V
Gate 2 to Source cut-off voltage	V_{G2SC}	$V_{DS} = 10V$, $V_{G1S} = 4V$, $I_D = 100\mu A$		- 0.4	-3	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 10V$, $I_D = 10mA$, $V_{G2S} = 4V$, $f = 1kHz$	17	23		mS
Input capacitance (Common Source)	C _{iss}	$V_{DS} = 10V, V_{G1S} = V_{G2S} = -5V$ f = 1MHz	2.7	3.8	5.3	pF
Output capacitance (Common Source)	Coss		1	1.4	2.2	pF
Reverse transfer capacitance (Common Source)	C _{rss}			0.02		pF
Parama anim	PG ₁	$V_{DS} = 8V$, $I_D = 8mA$, $V_{G2S} = 3V$ f = 195 to 205MHz (Sweep)	20	23	25	dB
Power gain PO	PG_2	$V_{DS} = 8V$, $I_D = 8mA$, $V_{G2S} = 3V$ f = 45 to 55MHz (Sweep)	20	23	25	dB
Noise figure	NF ₁ *1	$V_{DS} = 8V$, $I_D = 8mA$, $V_{G2S} = 3V$ f = 195 to 205MHz (Sweep)		2	3.2	dB
	NF ₂ *1	$V_{DS} = 8V, I_D = 8mA, V_{G2S} = 3V$ f = 45 to 55MHz (Sweep)		2.8	3.2	dB

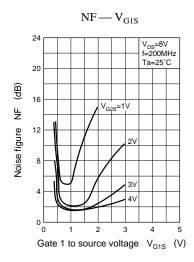
^{*1} Min value of NF at max PG.

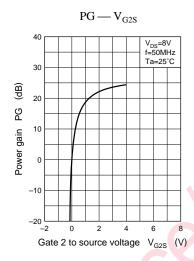
 $^{^{*2}}$ I_{DSS} rank classification

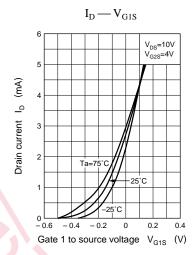
Rank	Q	R
I _{DSS} (mA)	0.8 to 7	4 to 15
Marking Symbol	3EQ	3ER



2 Panasonic







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